

# Time for ALD Metals: Enabling the next generation of leading-edge devices

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ALD, a unique deposition technique, is attracting more and more interest in the industry. With the characteristics of precise thickness control, extremely high conformality, low temperature, ALD plays an important role in the current technology and will become more crucial for the next leading edge devices. Several ALD key innovations will be discussed. With these innovations, ALD metals could enable the future scaling of microchip technology.

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